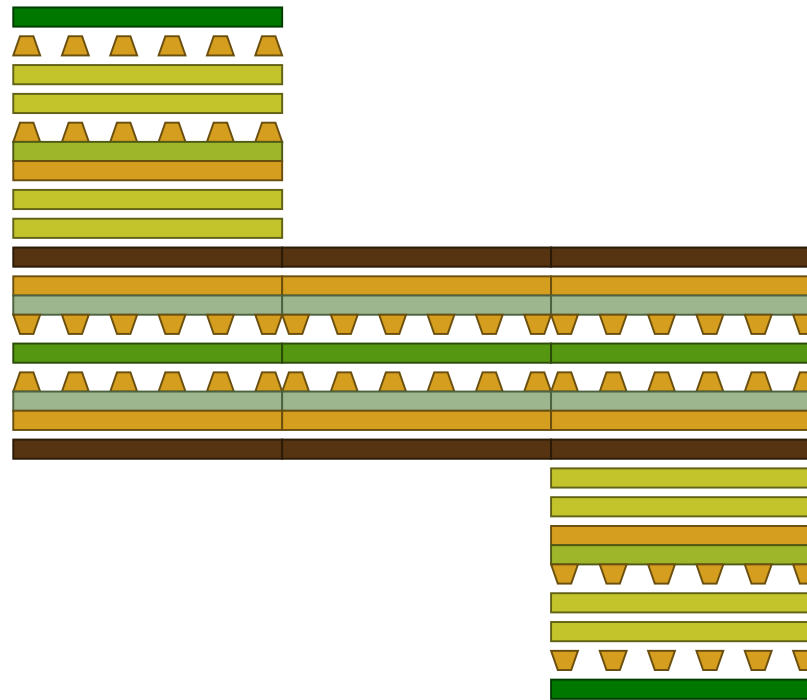



Bill of Materials



Rigid 1

Flex

Rigid 2

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Author: Richard Attrill						
Department: Engineering						
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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
1		Liquid Photolmageable Mask			25.000		4.000	0.0200	
		Copper Foil	Signal	17.780	48.260				
2		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
3		FR4 Core	Signal	18.000	18.000				
		FR4 Core	Plane	125.000	125.000	50.000	4.200	0.0195	
4		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
5		Coverlay		50.000	50.000		3.500	0.0195	
		Flex Core	Plane	18.000	18.000				
6		Flex Core	Signal	50.000	50.000	0.000	4.200	0.0195	
		Flex Core	Plane	18.000	18.000				
7		Coverlay		50.000	50.000		3.500	0.0195	
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
8		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
		FR4 Core	Plane	18.000	18.000				
9		FR4 Core	Signal	125.000	125.000	50.000	4.200	0.0195	
		FR4 Core	Plane	18.000	18.000				
10		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
		Copper Foil	Signal	17.780	48.260				
		Liquid Photolmageable Mask			25.000		4.000	0.0195	

1273.52

Copper Thickness = 240.520 | Dielectric Thickness = 1033.000 | Solder Mask Thickness = 50.000 | Stack Up Thickness = 1273.520 | Stack Up Thickness with Soldermask = 1323.520
Stack Up Cost = 22.00

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid Photolmageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Generic		Copper Foil	Copper		2	1.00	2.00	2	2.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00
Polar Samples	FC/001	Flex Core	Poly	600-001	2	2.00	4.00	2	4.00
Polar Samples	BP/002	Bondply 3	Dielectric	400-002	1	1.00	1.00	1	1.00
							22.00	22.00	


No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 22.00 |

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Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost				
Polar Samples	SM/001	Liquid Photoimageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00				
Layer	Generic	Stack up	Copper Foil	Copper	Copper Layer Type	1.00	1.00	2	2.00	Resin Content	ϵ_r	Loss Tangent	Impedance ID
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00				
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00				
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00				
Polar Samples	FC/001	Flex Core	Poly	600-001	2	2.00	4.00	2	4.00				
Polar Samples	BP/002	Bondply 3	Dielectric	400-002	1	1.00	1.00	1	1.00				
								22.00	22.00				

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 22.00 |
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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
		Liquid PhotoImageable Mask			25.000		4.000	0.0200	
1		Copper Foil	Signal	17.780	48.260				
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
2			Signal	18.000	18.000				
3		FR4 Core		125.000	125.000	50.000	4.200	0.0195	
			Plane	18.000	18.000				
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
4		Coverlay		50.000	50.000		3.500	0.0195	
			Plane	18.000	18.000				
5		Flex Core		50.000	50.000	0.000	4.200	0.0195	
			Signal	18.000	18.000				
6		Bondply 3		75.000	75.000	60.000	4.000	0.0195	
			Signal	18.000	18.000				
7		Flex Core		50.000	50.000	0.000	4.200	0.0195	
			Plane	18.000	18.000				
		Coverlay		50.000	50.000		3.500	0.0195	

810.26

Copper Thickness = 156.260 | Dielectric Thickness = 654.000 | Solder Mask Thickness = 25.000 | Stack Up Thickness = 810.260 | Stack Up Thickness with Soldermask = 835.260
Stack Up Cost = 14.50

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid PhotoImageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Generic		Copper Foil	Copper		2	1.00	2.00	2	2.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00
Polar Samples	FC/001	Flex Core	Poly	600-001	2	2.00	4.00	2	4.00
Polar Samples	BP/002	Bondply 3	Dielectric	400-002	1	1.00	1.00	1	1.00
							22.00	22.00	

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 22.00 |

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Department: Engineering							
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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	ϵ_r	Loss Tangent	Impedance ID
4		Coverlay		50.000	50.000		3.500	0.0195	
		Flex Core	Plane	18.000	18.000				
5			Signal	50.000	50.000	0.000	4.200	0.0195	
			Bondply 3		18.000	18.000			
6			Signal	75.000	75.000	60.000	4.000	0.0195	
			Flex Core	Plane	18.000	18.000			
7			Signal	50.000	50.000	0.000	4.200	0.0195	
		Flex Core	Plane	18.000	18.000				
		Coverlay		50.000	50.000		3.500	0.0195	

Copper Thickness = 72.000 | Dielectric Thickness = 275.000 | Solder Mask Thickness = 0.000 | Stack Up Thickness = 347.000 | Stack Up Thickness with Soldermask = 347.000
Stack Up Cost = 7.00

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid PhotoImageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
	Generic	Copper Foil	Copper		2	1.00	2.00	2	2.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00
Polar Samples	FC/001	Flex Core	Poly	600-001	2	2.00	4.00	2	4.00
Polar Samples	BP/002	Bondply 3	Dielectric	400-002	1	1.00	1.00	1	1.00
							22.00		22.00

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 22.00 |

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Layer	Stack up	Description	Copper Layer Type	Base Thickness	Processed Thickness	Resin Content	εr	Loss Tangent	Impedance ID
4		Coverlay		50.000	50.000		3.500	0.0195	
		Plane		18.000	18.000				
5		Flex Core	Signal	50.000	50.000	0.000	4.200	0.0195	
		Signal		18.000	18.000				
6		Bondply 3		75.000	75.000	60.000	4.000	0.0195	
		Signal		18.000	18.000				
7		Flex Core	Plane	50.000	50.000	0.000	4.200	0.0195	
		Plane		18.000	18.000				
8		Coverlay		50.000	50.000		3.500	0.0195	
		PrePreg 1080		63.500	63.500	60.000	4.200	0.0195	
	PrePreg 1080		63.500	63.500	60.000	4.200	0.0195		
	Plane		18.000	18.000					
9	FR4 Core	Signal	125.000	125.000	50.000	4.200	0.0195		
	Signal		18.000	18.000					
	PrePreg 1080		63.500	63.500	60.000	4.200	0.0195		
	PrePreg 1080		63.500	63.500	60.000	4.200	0.0195		
10	Copper Foil	Signal	17.780	48.260					
	Liquid Photolmageable Mask			25.000		4.000	0.0195		

Copper Thickness = 156.260 | Dielectric Thickness = 654.000 | Solder Mask Thickness = 25.000 | Stack Up Thickness = 810.260 | Stack Up Thickness with Soldermask = 835.260
Stack Up Cost = 14.50

Supplier	Supplier Description	Description	Type	Stock Number	Stack Quantity	Unit Cost	Stack Cost	Total Quantity	Total Cost
Polar Samples	SM/001	Liquid Photolmageable Mask	SolderMask	500-001	2	0.50	1.00	2	1.00
Generic		Copper Foil	Copper		2	1.00	2.00	2	2.00
Polar Samples	PP/001	PrePreg 1080	Dielectric	300-001	8	1.00	8.00	8	8.00
Polar Samples	CO/010	FR4 Core	FR4	400-010	2	2.00	4.00	2	4.00
Polar Samples	Clay/001	Coverlay	Cover	800-001	2	1.00	2.00	2	2.00
Polar Samples	FC/001	Flex Core	Poly	600-001	2	2.00	4.00	2	4.00
Polar Samples	BP/002	Bondply 3	Dielectric	400-002	1	1.00	1.00	1	1.00
							22.00	22.00	

No. of Panels = 1 | Circuits Per Panel = 1 | Price Per Circuit = 22.00 |

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Site:							